



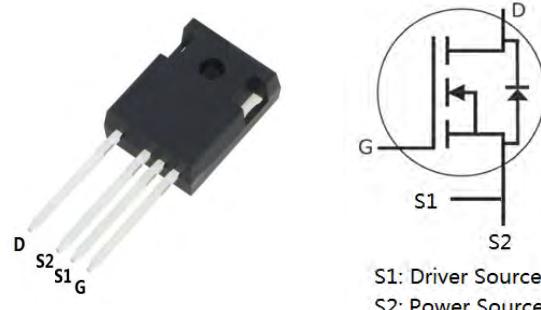
<b>V<sub>DS</sub></b>	=	<b>1700 V</b>
<b>R<sub>DS(on)</sub></b>	=	<b>45 mΩ</b>
<b>I<sub>D@25°C</sub></b>	=	<b>72 A</b>

## Features

- High Blocking Voltage with Low On-Resistance
- High Speed Switching with Low Capacitance
- Easy to Parallel and Simple to Drive

## Benefits

- Higher System Efficiency
- Reduced Cooling Requirements
- Increased Power Density
- Increased System Switching Frequency



TO-247-4L

## Applications

- Power Supplies
- High Voltage DC/DC Converters
- Motor Drives
- Switch Mode Power Supplies
- Pulsed Power applications

Part Number	Package
LGE3M45170Q	TO-247-4L

## Maximum Ratings ( $T_c=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Unit	Test Conditions	Note
$V_{DS\max}$	Drain-Source Voltage	1700	V	$V_{GS}=0\text{V}$ , $I_D=100\mu\text{A}$	
$V_{GS\max}$	Gate-Source Voltage	-10/+25	V	<b>Absolute maximum values</b>	
$V_{GSop}$	Gate-Source Voltage	-5/+20	V	<b>Recommended operational values</b>	
$I_D$	Continuous Drain Current	72	A	$V_{GS}=20\text{V}$ , $T_c=25^\circ\text{C}$	
		48		$V_{GS}=20\text{V}$ , $T_c=100^\circ\text{C}$	
$I_{D(pulse)}$	Pulsed Drain Current	160	A	Pulse width $t_p$ limited by $T_{J\max}$	
$P_D$	Power Dissipation	520	W	$T_c=25^\circ\text{C}$ , $T_j=150^\circ\text{C}$	
$T_J$ , $T_{STG}$	Operating Junction and Storage Temperature	-40 to +150	°C		


**Electrical Characteristics ( $T_c=25^\circ\text{C}$  unless otherwise specified)**

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions	Note
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	1700	/	/	V	$V_{GS}=0\text{V}, I_D=100\mu\text{A}$	
$V_{GS(\text{th})}$	Gate Threshold Voltage	2.0	2.6	4.0	V	$V_{DS}=V_{GS}, I_D=18\text{mA}$	Fig. 11
		/	1.8	/		$V_{DS}=V_{GS}, I_D=18\text{mA}, T_J=150^\circ\text{C}$	
$I_{DSS}$	Zero Gate Voltage Drain Current	/	1	100	$\mu\text{A}$	$V_{DS}=1700\text{V}, V_{GS}=0\text{V}$	
$I_{GSS+}$	Gate-Source Leakage Current	/	10	250	nA	$V_{DS}=0\text{V}, V_{GS}=25\text{V}$	
$I_{GSS-}$	Gate-Source Leakage Current	/	10	250	nA	$V_{DS}=0\text{V}, V_{GS}=-10\text{V}$	
$R_{DS(\text{on})}$	Drain-Source On-State Resistance	/	45	70	$\text{m}\Omega$	$V_{GS}=20\text{V}, I_D=50\text{A}$	
		/	90	/		$V_{GS}=20\text{V}, I_D=50\text{A}, T_J=150^\circ\text{C}$	
$g_{fs}$	Transconductance	/	25.8	/		$V_{DS}=20\text{V}, I_D=50\text{A}$	Fig. 4,5,6
		/	27.0	/		$V_{DS}=20\text{V}, I_D=50\text{A}, T_J=150^\circ\text{C}$	
$C_{iss}$	Input Capacitance	/	3550	/	pF	$V_{GS}=0\text{V}$	Fig. 15,16
$C_{oss}$	Output Capacitance	/	165	/		$V_{DS}=1000\text{V}$	
$C_{rss}$	Reverse Transfer Capacitance	/	6.1	/		f=1MHz	
$E_{oss}$	$C_{oss}$ Stored Energy	/	101	/	$\mu\text{J}$	$V_{AC}=25\text{mV}$	
$E_{ON}$	Turn-On Switching Energy	/	3.1	/	$\mu\text{J}$	$V_{DS}=1200\text{V}, V_{GS}=-5\text{V}/20\text{V}$	
$E_{OFF}$	Turn-Off Switching Energy	/	1.1	/		$I_D=30\text{A}, R_g=2.5\Omega, L=200\mu\text{H}$	
$t_{d(on)}$	Turn-On Delay Time	/	27	/	ns		
$t_r$	Rise Time	/	32	/		$V_{DS}=1200\text{V}, V_{GS}=-5\text{V}/20\text{V}, I_D=30\text{A}$	
$t_{d(off)}$	Turn-Off Delay Time	/	36	/		$R_g=2.5\Omega, R_L=20\Omega$	
$t_f$	Fall Time	/	10	/			
$R_{G(\text{int})}$	Internal Gate Resistance	/	2.6	/	$\Omega$	f=1MHz, $V_{AC}=25\text{mV}$	
$Q_{GS}$	Gate to Source Charge	/	54	/	nC	$V_{DS}=1200\text{V}$	
$Q_{GD}$	Gate to Drain Charge	/	25	/		$V_{GS}=-5\text{V}/20\text{V}$	
$Q_G$	Total Gate Charge	/	193	/		$I_D=50\text{A}$	

**Reverse Diode Characteristics**

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
$V_{SD}$	Diode Forward Voltage	3.6	/	V	$V_{GS}=-5\text{V}, I_F=25\text{A}$	Fig. 8,9,10
		3.3	/		$V_{GS}=-5\text{V}, I_F=25\text{A}, T_J=150^\circ\text{C}$	
$I_s$	Continuous Diode Forward Current	/	72	A	$T_c=25^\circ\text{C}$	
$t_{rr}$	Reverse Recover Time	55	/	ns	$V_R=1200\text{V}, I_{SD}=50\text{A}$	
$Q_{rr}$	Reverse Recovery Charge	220	/	nC		
$I_{rrm}$	Peak Reverse Recovery Current	6.7	/	A		

**Reverse Diode Characteristics**

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
$R_{\theta JC}$	Thermal Resistance	0.24	0.28	$^\circ\text{C}/\text{W}$		



## Typical Performance

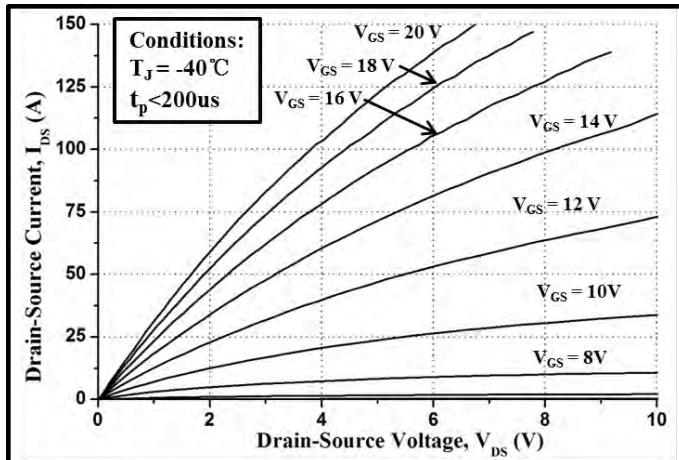


Figure 1. Output Characteristics  $T_J = -40^\circ\text{C}$

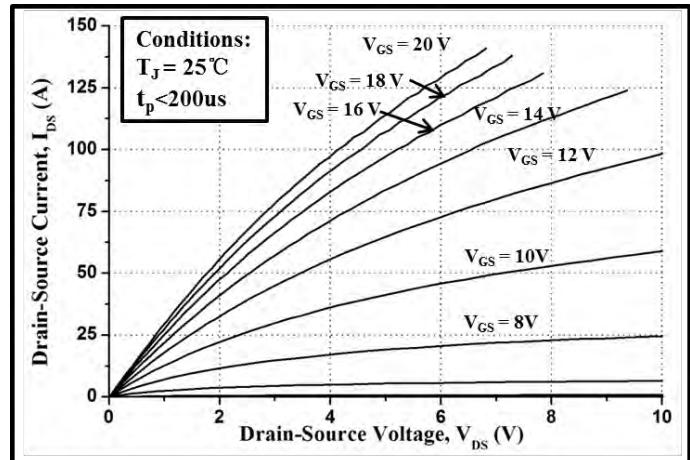


Figure 2. Output Characteristics  $T_J = 25^\circ\text{C}$

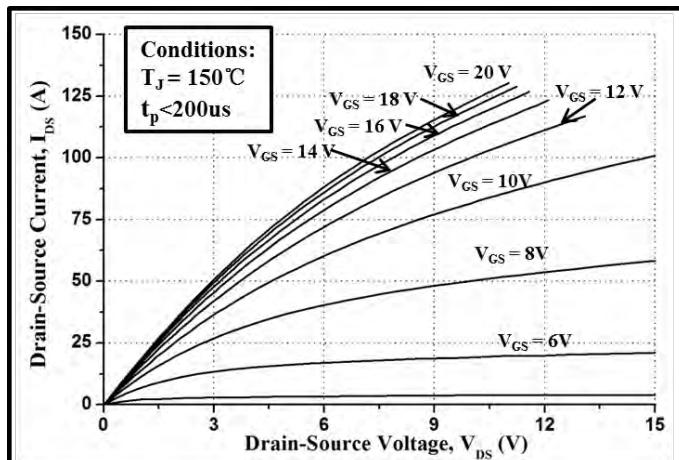


Figure 3. Output Characteristics  $T_J = 150^\circ\text{C}$

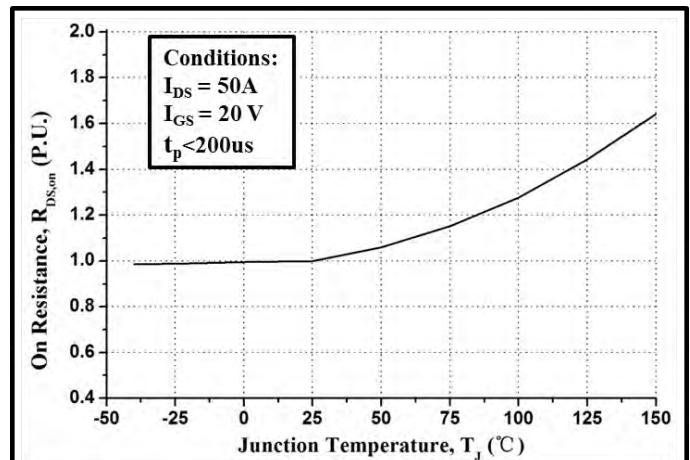


Figure 4. Normalized On-Resistance vs. Temperature

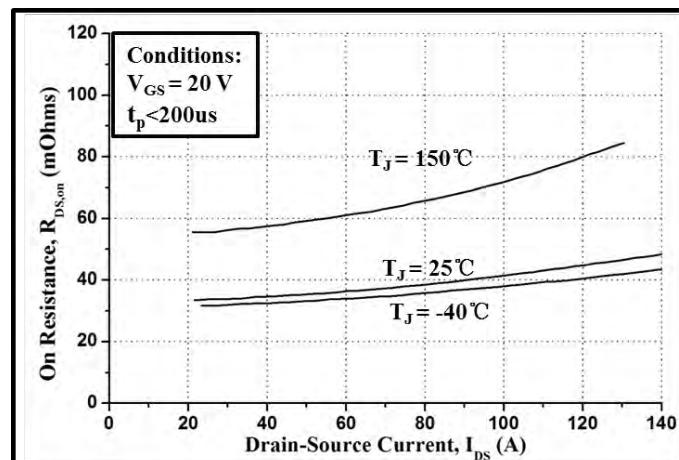


Figure 5. On-Resistance vs. Drain Current  
For Various Temperatures

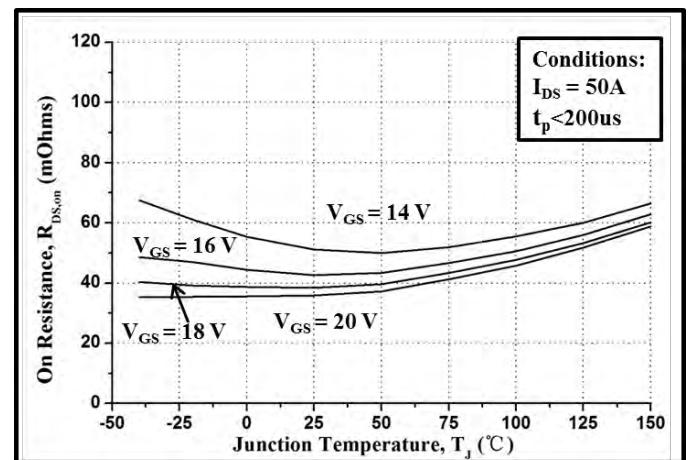


Figure 6. On-Resistance vs. Temperature  
For Various Gate Voltage



## Typical Performance

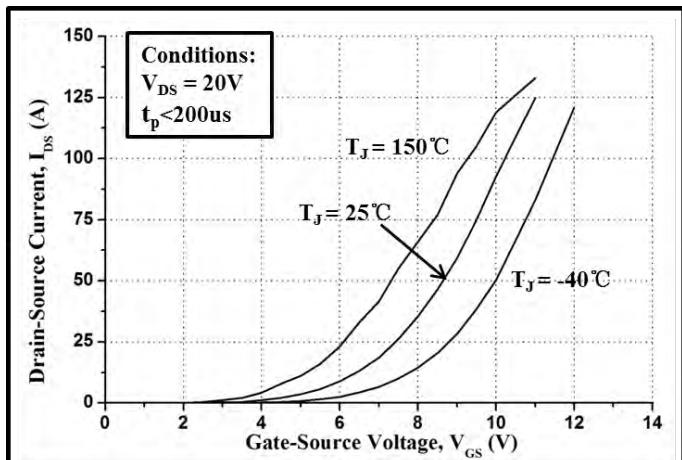


Figure 7. Transfer Characteristic for  
Various Junction Temperatures

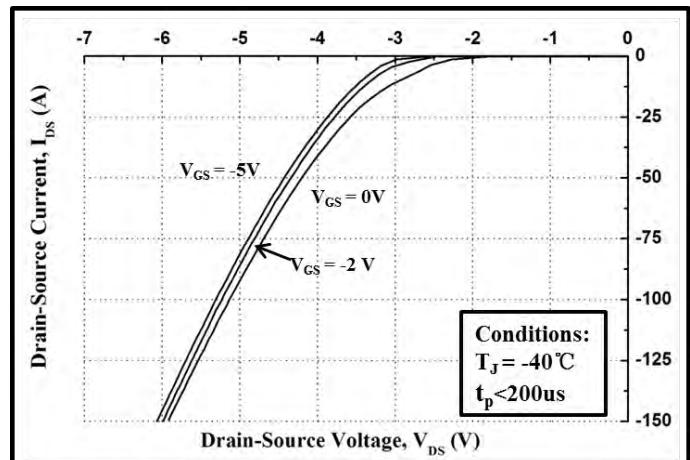


Figure 8. Body Diode Characteristic at  $-40^\circ C$

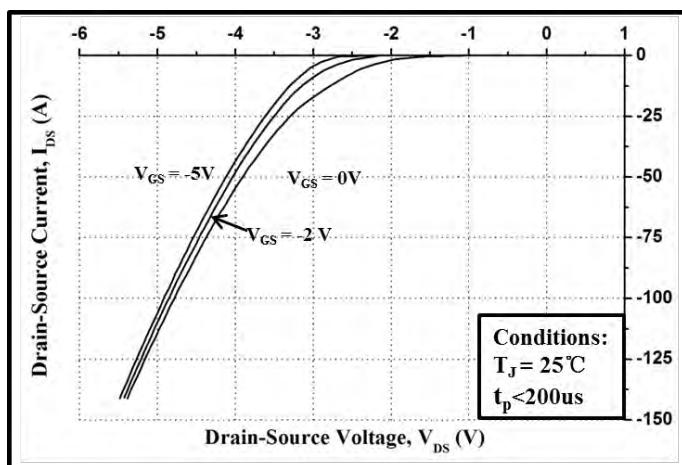


Figure 9. Body Diode Characteristic at  $25^\circ C$

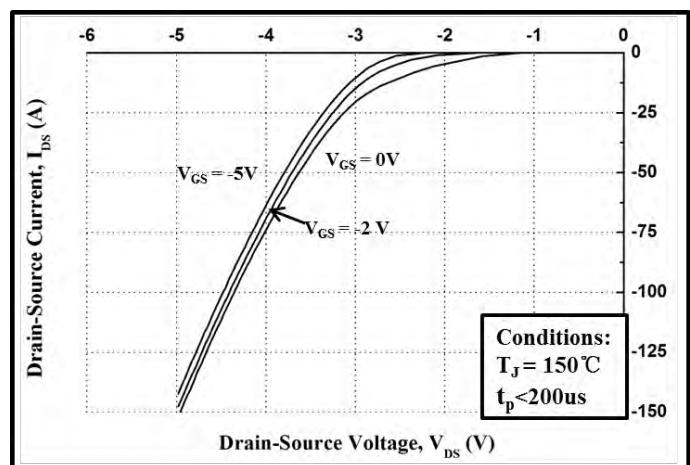


Figure 10. Body Diode Characteristic at  $150^\circ C$

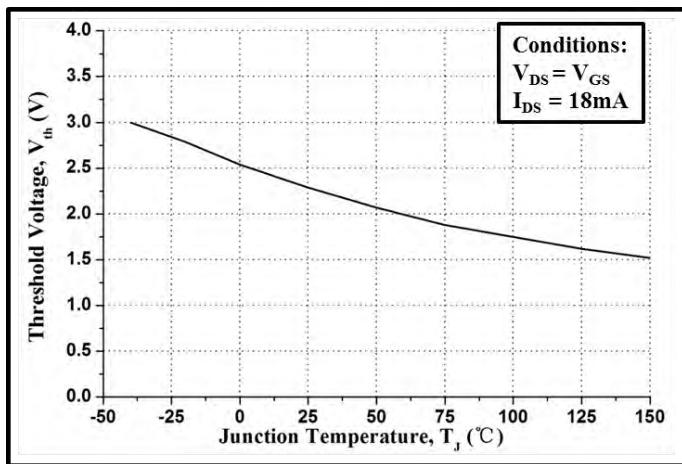


Figure 11. Threshold Voltage vs. Temperature

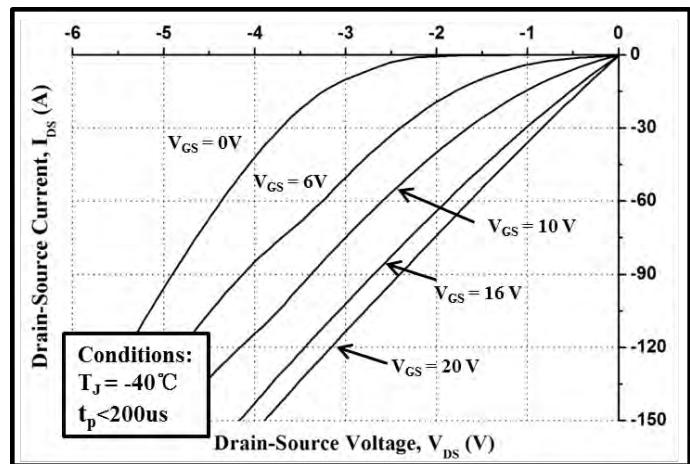
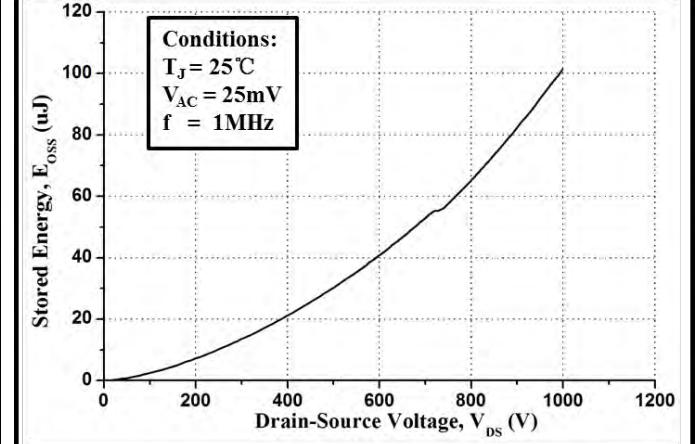
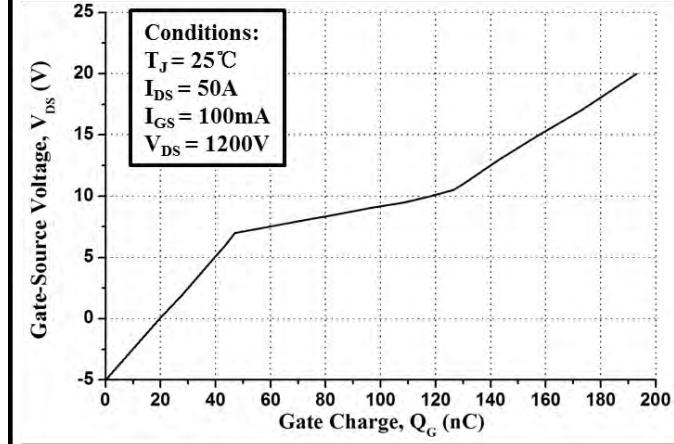
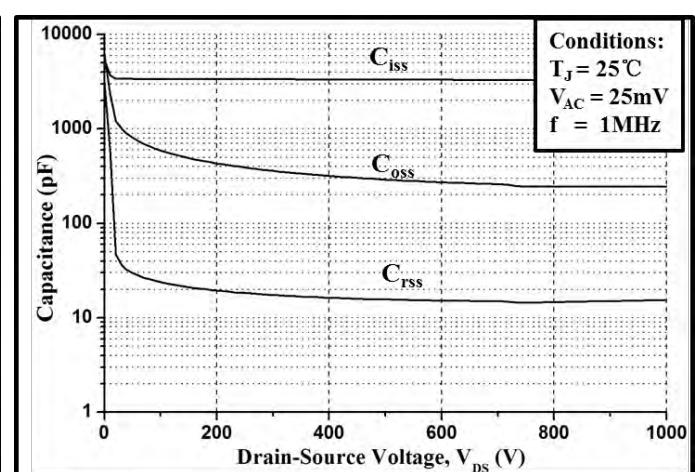
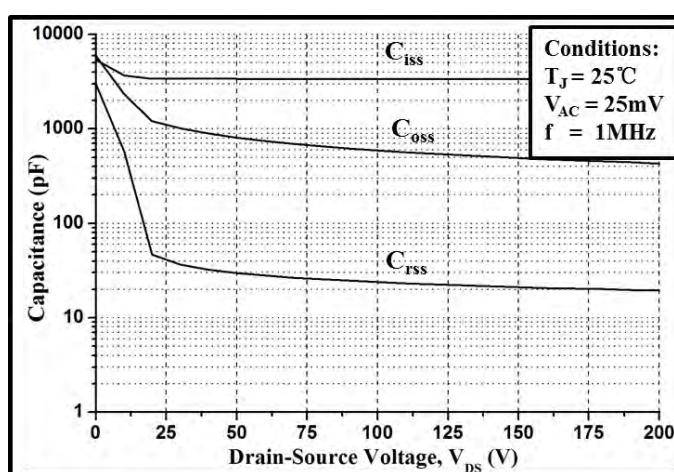
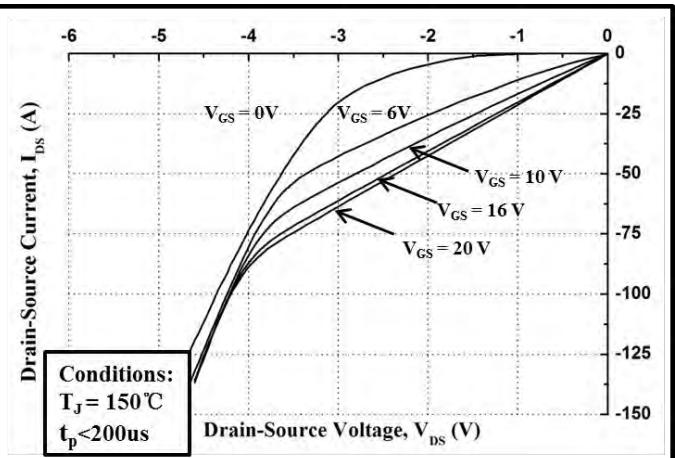
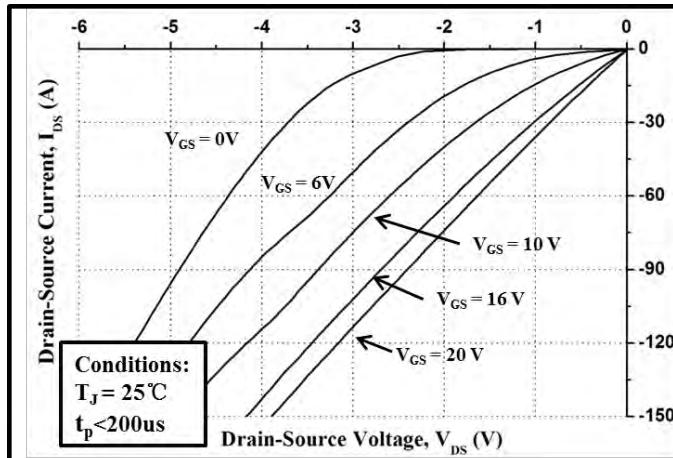


Figure 12. 3rd Quadrant Characteristic at  $-40^\circ C$



## Typical Performance



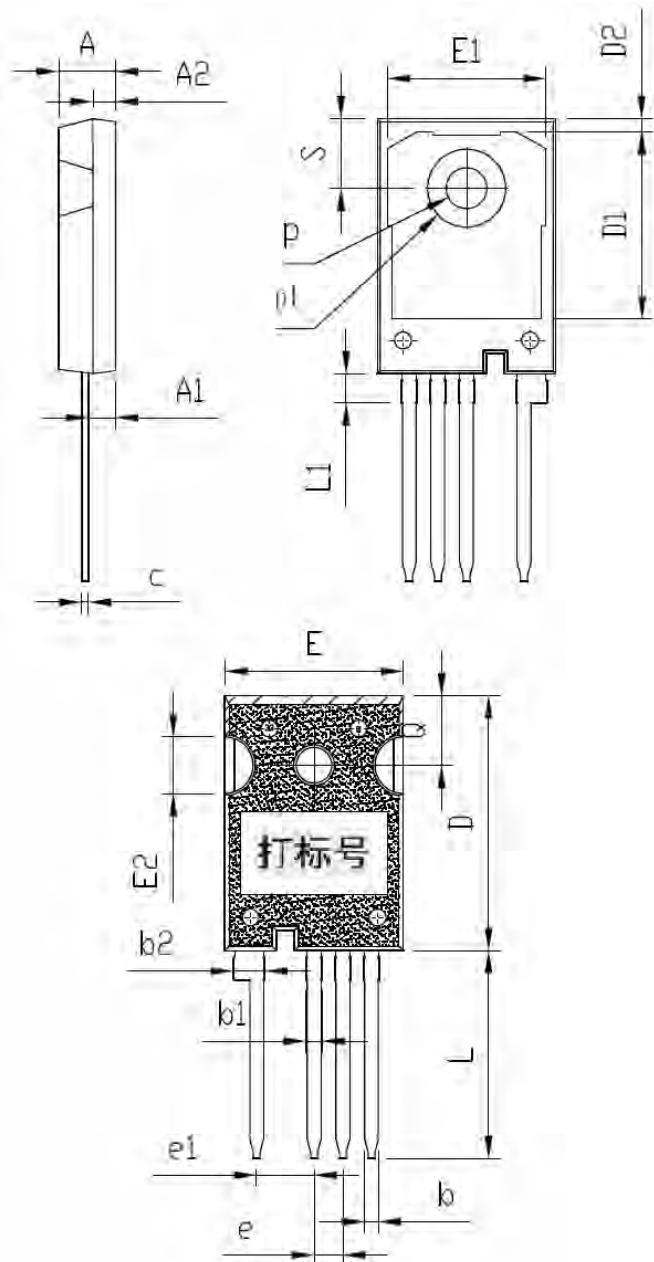


LGE3M45170Q

SiC Power MOSFET



Package TO-247-4



SYMBOLS	DIMENSIONS IN MILLIMETERS		
	MIN	NOM	MAX
A		5.00	
A1		2.40	
A2		2.00	
b		1.20	
b1		1.30	
b2		2.65	
c		0.6	
D		22.54	
D1		16.50	
D2		1.17	
e		2.54	
e1		5.08	
E		15.80	
E1		14.00	
E2		5.00	
L		18.38	
L1		2.58	
p		3.60	
p1		6.80	
Q		6.15	
S		6.15	